



OPEN  
Cloud Platform

Tencent



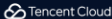
Tencent Cloud

# *OCP China Technology Day*

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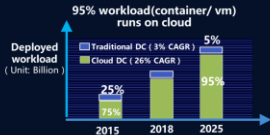


# *Powering The Open Data Center Revolution*

*OCP China Technology Day*

中国 OCP 技术研讨会

# Intelligent World Requires Enormous Computing Power



Data source : Cisco

High demand on the scale of data processing and efficiency



~20 trillion images /day

20 Million

Complete processing  $\approx$  2.3million



1000ps/s

Development of AI drives computing capability significantly

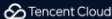


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# Solutions



Open



Converge



Agile



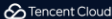
Ecosystem

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# Open Platform, Making Ecosystem More Open

Open Hardware

Open Software

Embrace  
Open

Member: Facebook, Inspur,  
Google, Microsoft



Over billion deployment

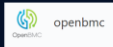
Members: Baidu, Tencent,  
Alibaba, Intel, Inspur



Millions of nodes deployed



OpenPower



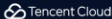
Rack Level Management

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# Open Platform, Making Ecosystem More Open

Beneficial

Open Design  
Platform



Accelerate  
Innovation



Decrease TCO



Power  
consumption



Lower Failure  
Rate



Easy to Join

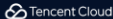
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# Goal for Open Platform



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No.1 Server supplier for Alibaba

Alibaba e-Commerce Platform is Running on Inspur

ODCC Rack

Peak of system transaction reached 175,000 orders per second



Over 80% of Baidu's hyperscale rack-level servers

Deploying 10,000 nodes per day

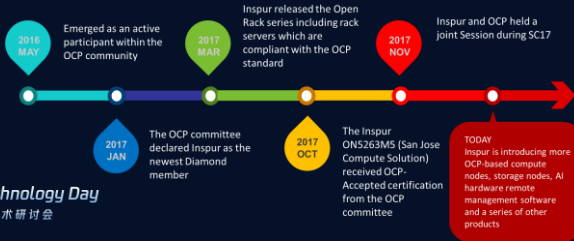
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# Momentum of OCP & Inspur



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# Open Rack Architecture Comparison

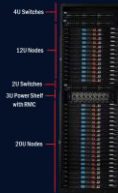


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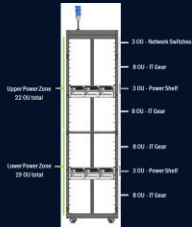
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Share the same inner dimension : 21-inch wide  
Front maintenance : computing nodes, PSU, Switch,  
Cables can be maintained from cold aisle

Item	SR (Scorpio Unit)	OCP (Open Unit)
1U Height (mm)	46.5 (Scorpio Unit)	48 (Open Unit)
Rack Height	42/46 SU	41 OU
Server Node Width	21"	21"
Device Space	36/40 SU	32 OU
Switch	3 SU	3 OU
Power	3 SU	6 OU
Bus bar	1 pair(left)	3 pair
Unified Cooling	Yes	No
Unified Mgmt	Yes	No



Inspur SR Rack



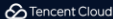
Open Rack V2

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# Converge ODCC Rack and OCP Rack



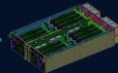
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ODCC Form Factor



OCP Form Factor



Convert ODCC storage and GPU nodes to OCP, with key components shared  
Design cycle shortened 60%, high reliability and cost efficiency

Component	SR Storage Node	OCP Storage Node
Chassis	N	N
HDD Tray	Share	Share
Controller Board	Share	Share
HDD Backplane	N	N
Power Distribution Board	N	N

Component	SR GPU Node	OCP GPU Node
Chassis	N	N
GPU Switch Board	Share	Share
Expansion Board	Share	Share
Power Distribution Board	N	N

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# Inspur OCP Rack Level Product Overview



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## Compute



NEW

### I/O Balance

- 2x 2.5" HDD or NVMe
- 2x M.2
- 1x FHH(x16) : CPU0
- 1x FHH(x16) : CPU1



NEW

### High Expansion

- 4x 2.5" HDD or NVMe
- 1x M.2
- 3x FHH(x16) : CPU0



NEW

### Density Computing

- 2x M.2
- Expansion Slot:
- 1x FHH(x16) : CPU0



MP

### Energy Efficiency

- 1x 2.5" HDD
- 1x M.2
- 1x FHH(x16) : CPU0
- 1x FHH(x16) : CPU1



## Storage



NEW

- 20U Form Factor
- Two drive tray design
- 34" HDDs or SSD
- Each drive support Hot-plug



## AI



NEW

- GPU Box
- 40U Form Factor
- 16 PCIe GPU Cards



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# Inspur OCP Compute Family



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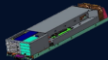
## Converged Computing Architecture

### Converge Architecture

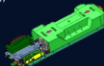
- Unified MB Design to cover 4 Types Application
- Cover High Expansion, Resource Balance, Energy Efficiency and Density Computing



I/O  
Balance



High  
Expansion



Energy  
Efficiency



Density  
Computing

### High Density & High Performance

- High density architecture to support 20U three Node and 10U three Node
- High performance computing capability

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# Inspur OCP JBOD Storage



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## Storage Density and Cost Efficiency



### High Storage Density

- 20U 34\*HDDs, improve 13% storage capacity

### Flexiable Architecture

- Dual Separate Storage tray, 17 drives per tray
- Each tray support SATA and SSD, maintain individuly



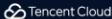
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# Inspur OCP AI Product



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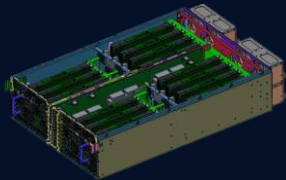
## Scalable and Leading Compute Architecture

Leading Compute Capability

40U 16\*GPU for training

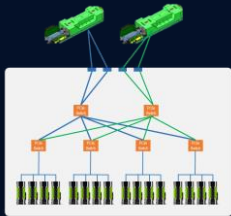
or 16\*FPGA for Inference

Optimization Architecture for AI



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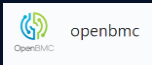
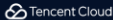
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# Hardware Management For OCP Rack



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WebUI to monitor system status



Redfish/Restful Function , Support Redfish OCP Baseline Profile

## Component Firmware Life cycle Management

1. Version auto discovery
2. Intelligent update for BMC, BIOS, CPLD, FPGA etc.
3. Firmware rollback when error occurs.



## Fault Diagnosis

1. System Fault rapid diagnosis.
2. Output the detailed fault records and recommendations.
3. BMC Subsystem fault diagnosis

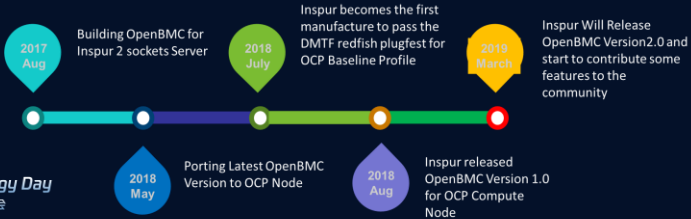
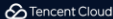


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# Inspur's OpenBMC Roadmap



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# OCP Global Summit

San Jose, CA  
March 14-15, 2019



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